

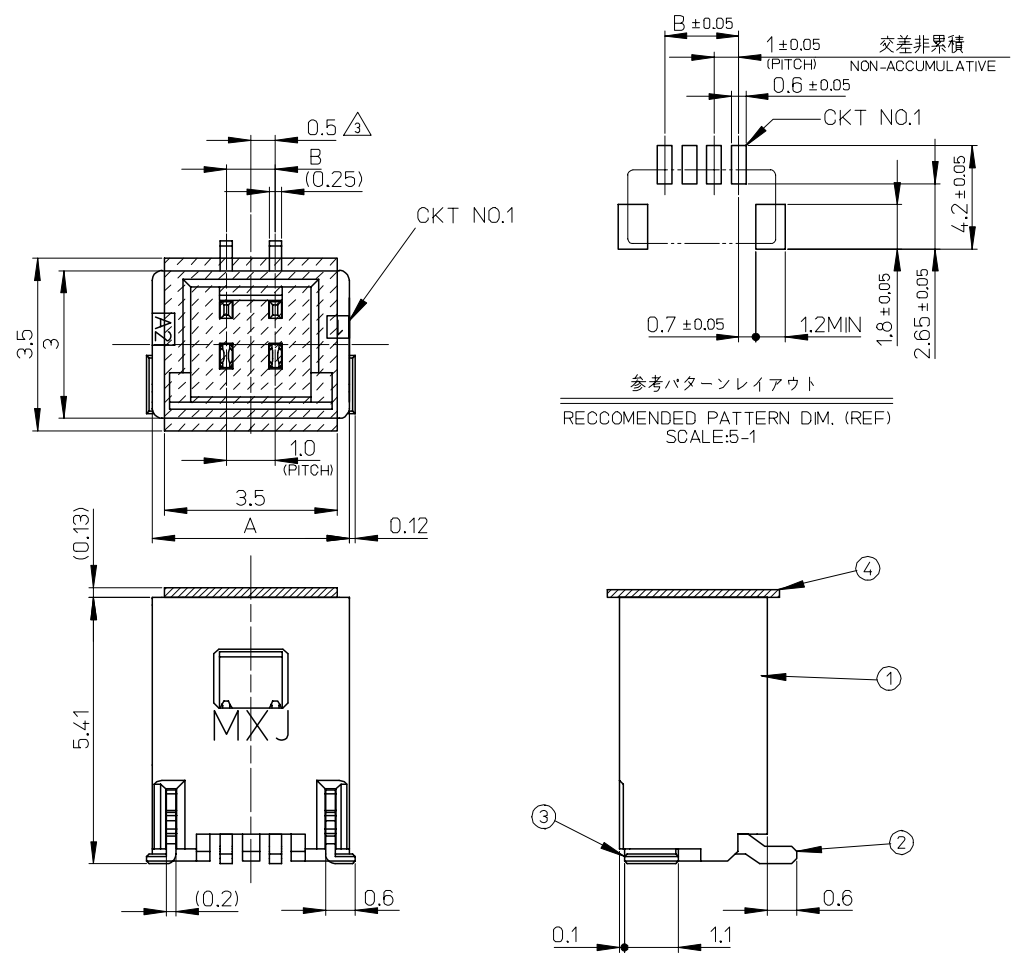
番号 NO.	部品 PART	材質 MATERIAL
①	ウェハー WAFER	46ナイロン UL94V-0 色:自然色 46 NYLON, UL94V-0, COLOR:NATURAL
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)
④	カバーテープ COVER TAPE	ポリイミドテープ POLYIMIDE TAPE

NOTES.

- 嵌合相手: 501330-****
MATE WITH: 501330-****
- ソルダーピン及びネイル平坦度は、0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
- △ 極数=偶数に適用
APPLY FOR CKT SIZE=EVEN
- 4.6~15極については、SD-501331-002を参照下さい。
REFER TO SD-501331-002 ABOUT 6-15CKT.
- ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.

※対応可能な極数は、別途お問い合わせ下さい。

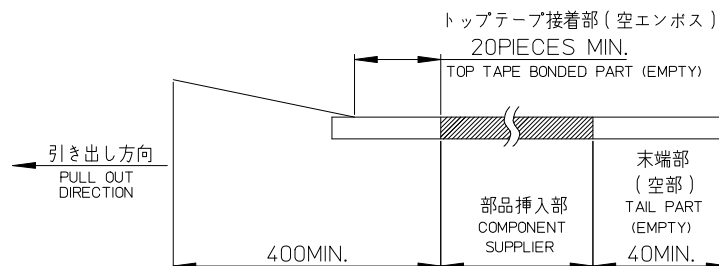
4.0	7.0	501331-0509	5	501331-**09
3.0	6.0	501331-0409	4	
2.0	5.0	501331-0309	3	
1.0	4.0	501331-0209	2	
B	A	MATERIAL NO.	CKT.	MODEL NO.



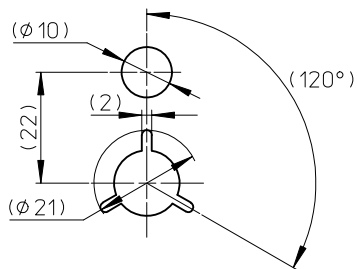
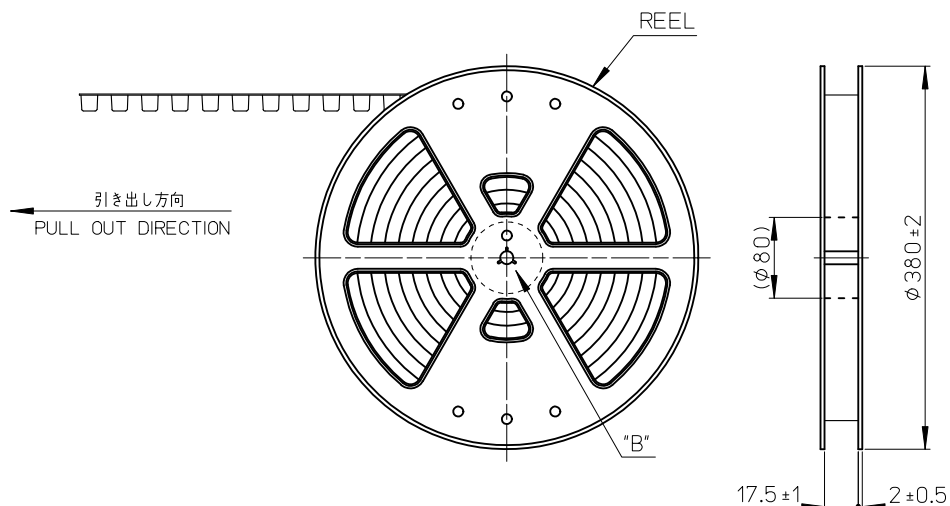
REVISED EC NO: J2007-2540 DRWN: A0YAGI CHKD: YMAEDA APPR: NUKITA	DESCRIPTION 2007/03/13 2007/03/13 2007/03/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY NYOSHIDA	DATE 2004/07/30	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) 2-5CKT		MOLEX INCORPORATED	
10 OVER 30 UNDER	± 0.25	CHECKED BY MYAGI	DATE 2004/07/30	APPROVED BY MIYAZAWA		DATE 2004/07/30	SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
30 OVER	± 0.3	ANGULAR ± 3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					

NOTES

1. 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
2. 梱包数量: 1100個/リール
NUMBER OF CONNECTORS: 1100PIECES/REEL
3. リードテープ長さ
LEAD TAPE LENGTH

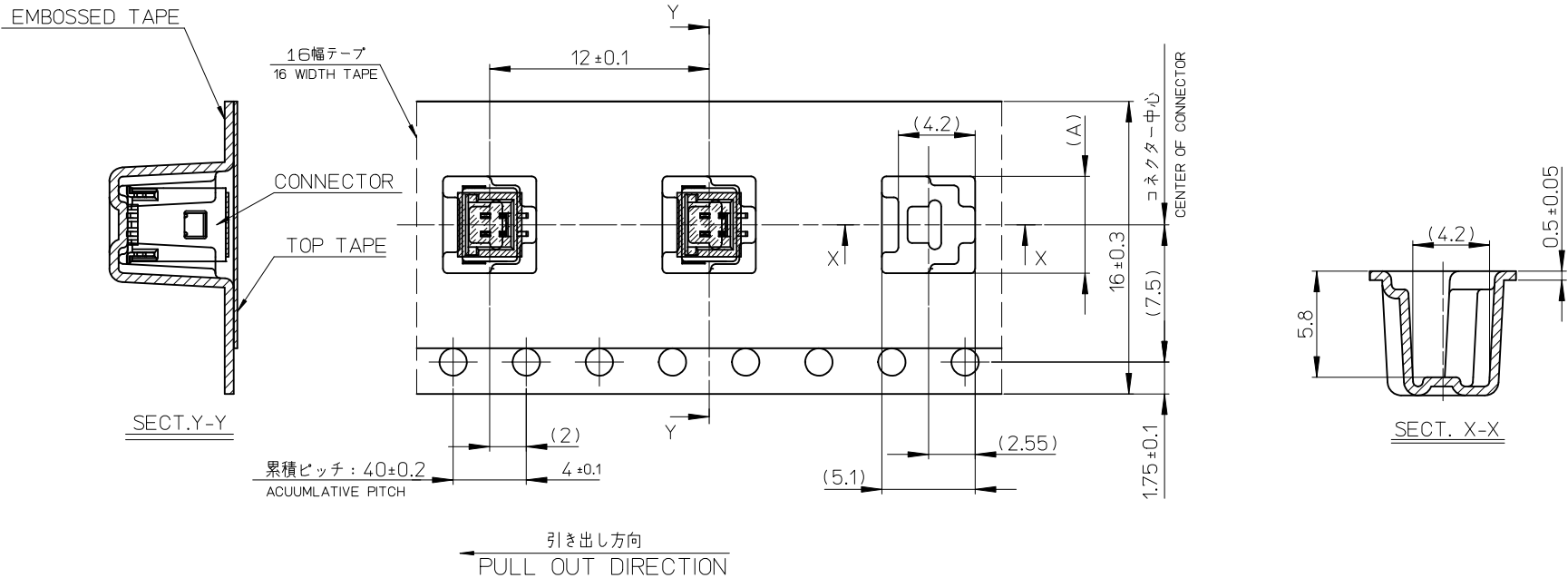


4. 材料
MATERIAL
キャリアテープ: ポリプロピレン
CARRIER TAPE: POLYPROPYLENE
トップテープ: PET、PE、REF
TOP TAPE
リール: ポリスチレン<リサイクル材を含む>
REEL: POLYSTYRENE <RECYCLE MATERIAL CONTAINED>
5. ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.
6. 本製品は乾燥剤入り、ハイバリア梱包仕様である。
(501331-0607~1507以外)
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.
(BESIDES 501331-0607~1507)



DETAIL "B"

REVISED EC NO: J2010-0951 DRWN: NITO 2009/12/16 CHKD: KASAKAWA 2010/01/05 APPR: NUKITA 2010/01/06	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY NYOSHIDA	DATE 2005/01/18	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG			
		10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/01/18	MOLEX INCORPORATED			
		30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/01/18	MATERIAL NO. SEE SHEET 2			
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DOCUMENT NO. SD-501331-003		SHEET NO. 1 OF 2			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									



8.3	501331-0509	501331-0507	5	501331-***7
7.3	501331-0409	501331-0407	4	
6.3	501331-0309	501331-0307	3	
5.3	501331-0209	501331-0207	2	
(A)	CONNECTOR	MATERIAL NO.	CKT.	MODEL NO.

REVISED EC NO: J2010-0951 DRWN: NITO 2009/12/16 CHKD: KASAKAWA 2010/01/05 APPR: NUKITA 2010/01/06	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY NYOSHIDA	DATE 2005/01/18	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG MOLEX INCORPORATED	
	10 OVER 30 UNDER	± 0.25	CHECKED BY MYAGI	DATE 2005/01/18		
	30 OVER	± 0.3	APPROVED BY ANODA	DATE 2005/01/18		
ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501331-003	SHEET NO. 2 OF 2	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						